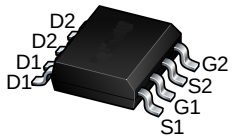
## Description

The XXW4886 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

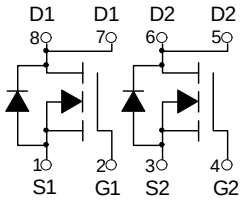



SOP-8

## General Features

$V_{DS}$ = 100V $I_D$ = 8A

$R_{DS(ON)}$ < 112mΩ @ $V_{GS}$=10V




Dual N-Channel MOSFET

## Application

Battery protection

Load switch

Uninterruptible power supply

## Absolute Maximum Ratings@$T_j$=25ºC(unless otherwise specified)

| Symbol | Parameter | Rating | Units |
|---|---|---|---|
| $V_{DS}$ | Drain-Source Voltage | 100 | V |
| $V_{GS}$ | Gate-Source Voltage | ±20 | V |
| $I_D$@$T_A$=25℃ | Drain Current, $V_{GS}$ @ 4.5V[3] | 8 | A |
| $I_D$@$T_A$=70℃ | Drain Current, $V_{GS}$ @ 4.5V[3] | 5 | A |
| $I_{DM}$ | Pulsed Drain Current[1] | 15 | A |
| $P_D$@$T_A$=25℃ | Total Power Dissipation | 1.5 | W |
| $T_{STG}$ | Storage Temperature Range | -55 to 150 | ℃ |
| $T_J$ | Operating Junction Temperature Range | -55 to 150 | ℃ |
| Rthj-a | Maximum Thermal Resistance, Junction-ambient[3] | 85 | ℃/W |

## Electrical Characteristics ($T_J$=25 ℃, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|---|---|---|---|---|---|---|
| $BV_{DSS}$ | Drain-Source Breakdown Voltage | $V_{GS}$=0V , $I_D$=250uA | 100 | --- | --- | V |
| $\triangle BV_{DSS}/\triangle T_J$ | BVDSS Temperature Coefficient | Reference to 25℃ , $I_D$=1mA | --- | 0.098 | --- | V/℃ |
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance[2] | $V_{GS}$=10V , $I_D$=2A | --- | 97 | 112 | mΩ |
| | | $V_{GS}$=4.5V , $I_D$=1A | --- | 106 | 120 | mΩ |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{GS}$=$V_{DS}$ , $I_D$ =250uA | 1.0 | 1.5 | 2.5 | V |
| $\triangle V_{GS(th)}$ | $V_{GS(th)}$ Temperature Coefficient | | --- | -4.57 | --- | mV/℃ |
| $I_{DSS}$ | Drain-Source Leakage Current | $V_{DS}$=80V , $V_{GS}$=0V , $T_J$=25℃ | --- | --- | 10 | uA |
| | | $V_{DS}$=80V , $V_{GS}$=0V , $T_J$=55℃ | --- | --- | 100 | |
| $I_{GSS}$ | Gate-Source Leakage Current | $V_{GS}$=±20V , $V_{DS}$=0V | --- | --- | ±100 | nA |
| gfs | Forward Transconductance | $V_{DS}$=5V , $I_D$=2A | --- | 12 | --- | S |
| $R_g$ | Gate Resistance | $V_{DS}$=0V , $V_{GS}$=0V , f=1MHz | --- | 2 | 4 | Ω |
| $Q_g$ | Total Gate Charge (10V) | $V_{DS}$=60V , $V_{GS}$=10V , $I_D$=2A | --- | 19.5 | --- | nC |
| $Q_{gs}$ | Gate-Source Charge | | --- | 3.2 | --- | |
| $Q_{gd}$ | Gate-Drain Charge | | --- | 3.6 | --- | |
| $T_{d(on)}$ | Turn-On Delay Time | $V_{DD}$=50V , $V_{GS}$=10V , $R_G$=3.3Ω $I_D$=1A | --- | 16.2 | --- | ns |
| $T_r$ | Rise Time | | --- | 3 | --- | |
| $T_{d(off)}$ | Turn-Off Delay Time | | --- | 44 | --- | |
| $T_f$ | Fall Time | | --- | 2.6 | --- | |
| $C_{iss}$ | Input Capacitance | $V_{DS}$=15V , $V_{GS}$=0V , f=1MHz | --- | 1535 | --- | pF |
| $C_{oss}$ | Output Capacitance | | --- | 60 | --- | |
| $C_{rss}$ | Reverse Transfer Capacitance | | --- | 37.4 | --- | |

## Diode Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|---|---|---|---|---|---|---|
| $I_S$ | Continuous Source Current[1,5] | $V_G$=$V_D$=0V , Force Current | --- | --- | 8 | A |
| $I_{SM}$ | Pulsed Source Current[2,5] | | --- | --- | 12 | A |
| $V_{SD}$ | Diode Forward Voltage[2] | $V_{GS}$=0V , $I_S$=1A , $T_J$=25℃ | --- | --- | 1.2 | V |

Note :
1.The data tested by surface mounted on a 1 inch$^2$ FR-4 board with 2OZ copper.
2.The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%
3.The EAS data shows Max. rating . The test condition is $V_{DD}$=25V,$V_{GS}$=10V,L=0.1mH,$I_{AS}$=11A
4.The power dissipation is limited by 175℃ junction temperature
5.The data is theoretically the same as $I_D$ and $I_{DM}$ , in real applications , should be limited by total power dissipation.

## Typical Characteristics

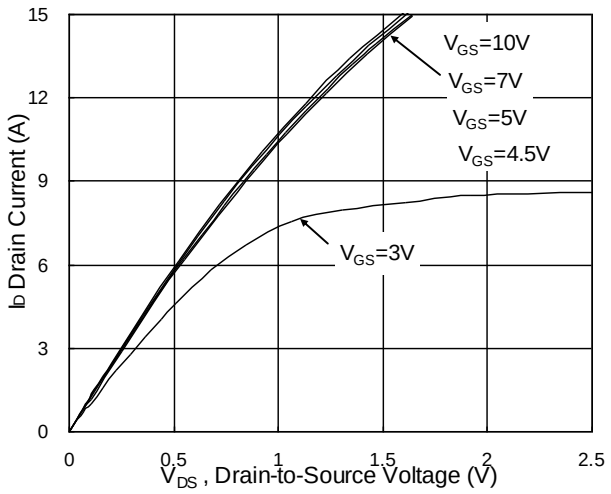



**Fig.1 Typical Output Characteristics**

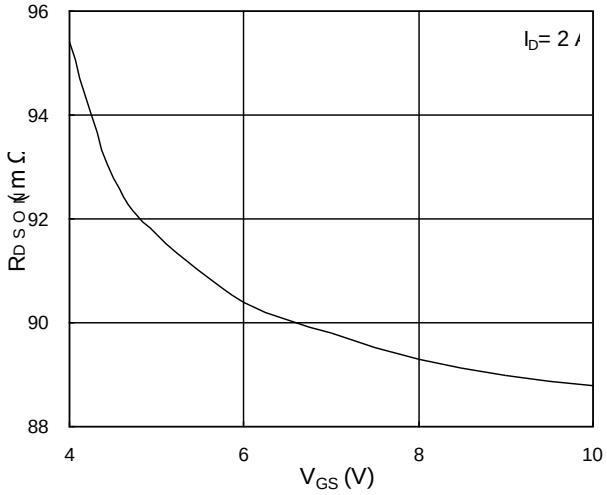



**Fig.2 On-Resistance vs. Gate-Source**

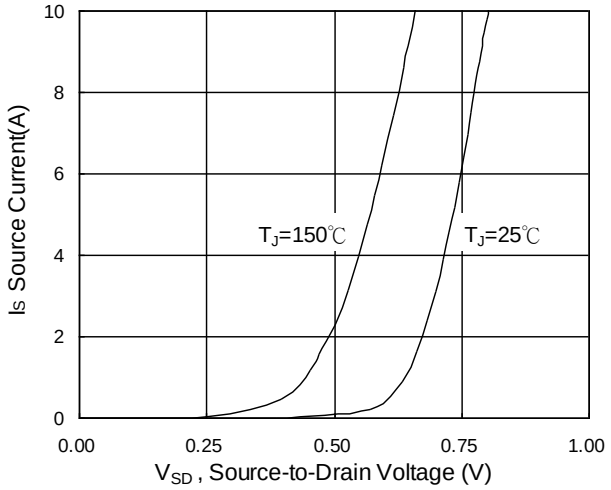



**Fig.3 Forward Characteristics Of Reverse**

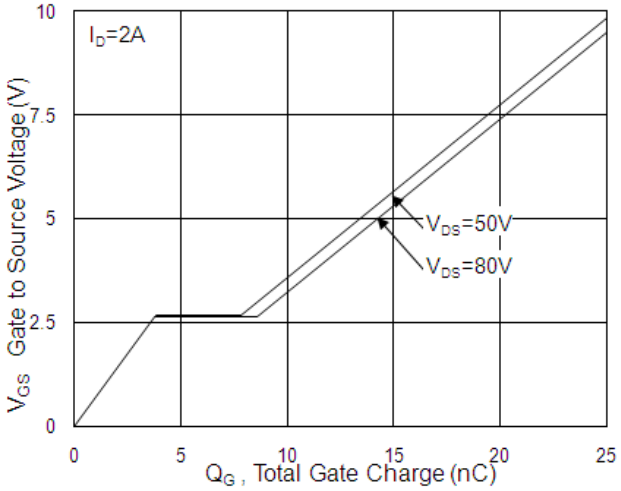



**Fig.4 Gate-Charge Characteristics**

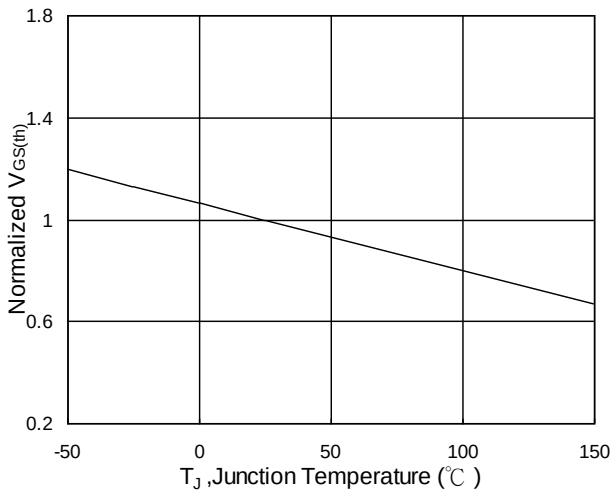



**Fig.5 Normalized $V_{GS(th)}$ vs. $T_J$**

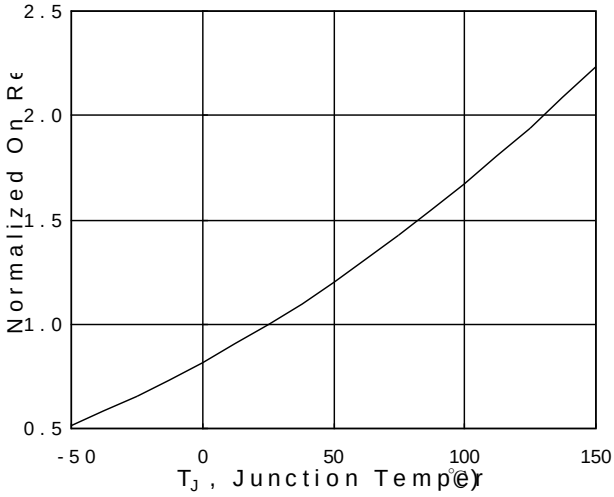



**Fig.6 Normalized $R_{DSON}$ vs. $T_J$**

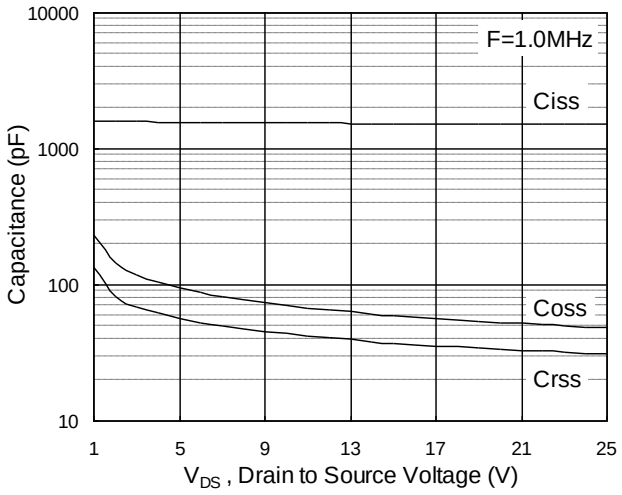



**Fig.7 Capacitance**

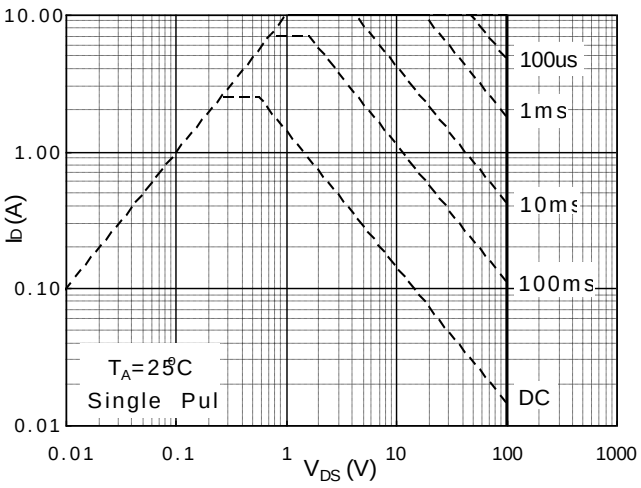



**Fig.8 Safe Operating Area**

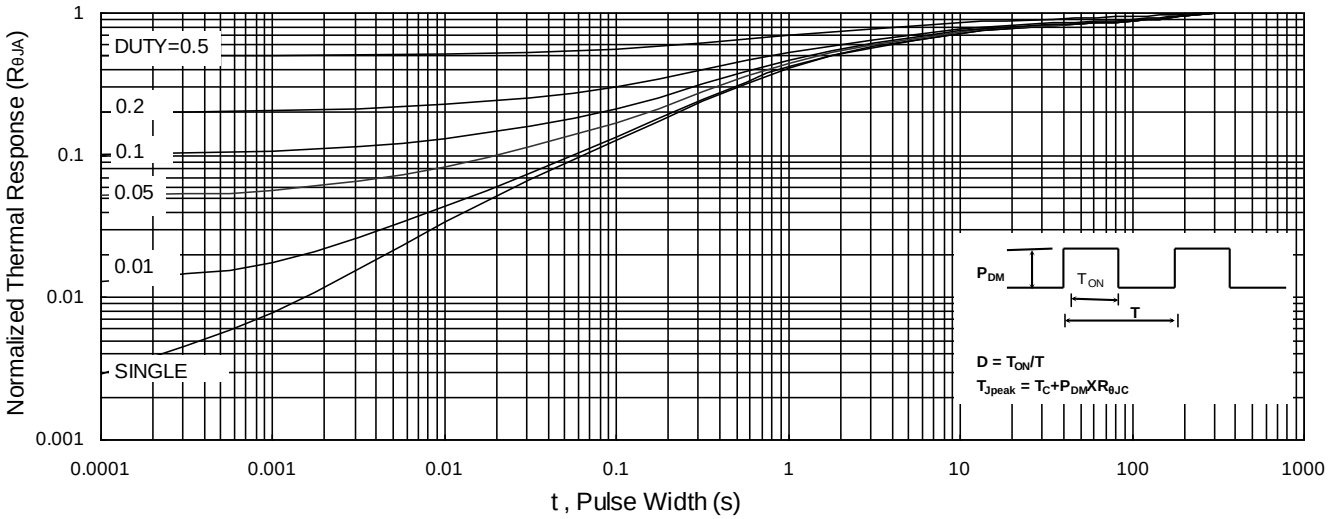



**Fig.9 Normalized Maximum Transient Thermal Impedance**

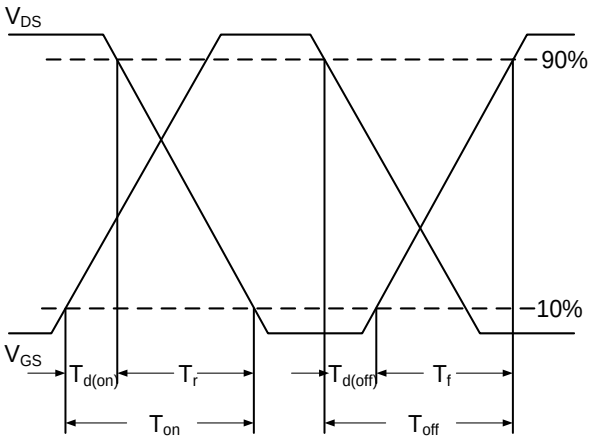



**Fig.10 Switching Time Waveform**

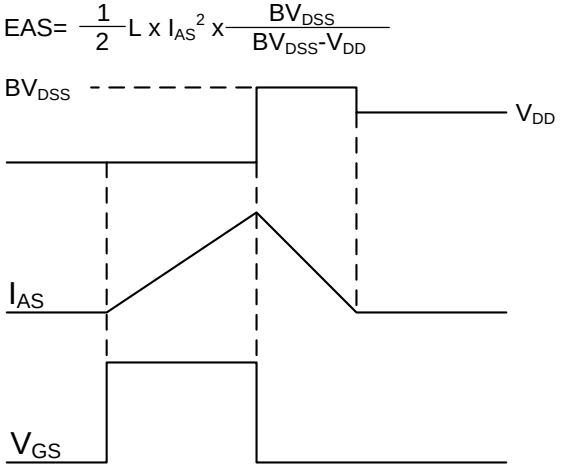
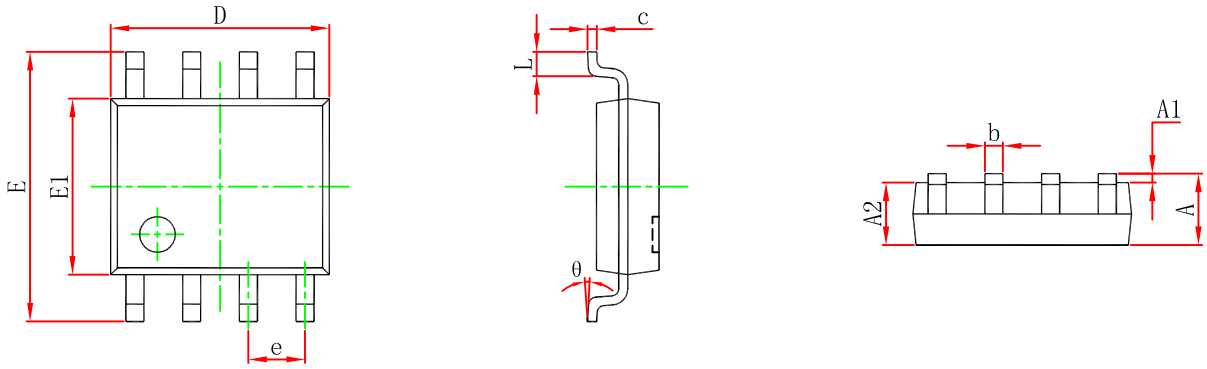
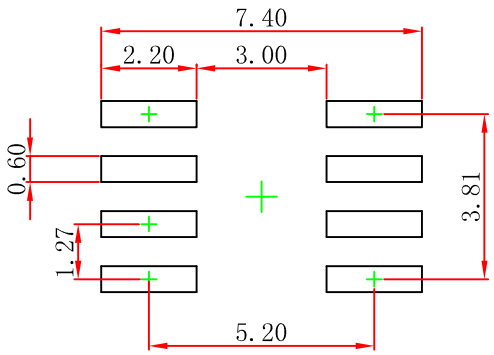



**Fig.11 Unclamped Inductive Switching Waveform**

## SOP-8 Package Outline Dimensions




| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|---|---|---|---|---|
| | **Min** | **Max** | **Min** | **Max** |
| A | 1.350 | 1.750 | 0.053 | 0.069 |
| A1 | 0.100 | 0.250 | 0.004 | 0.010 |
| A2 | 1.350 | 1.550 | 0.053 | 0.061 |
| b | 0.330 | 0.510 | 0.013 | 0.020 |
| c | 0.170 | 0.250 | 0.007 | 0.010 |
| D | 4.800 | 5.000 | 0.189 | 0.197 |
| e | 1.270 (BSC) | | 0.050 (BSC) | |
| E | 5.800 | 6.200 | 0.228 | 0.244 |
| E1 | 3.800 | 4.000 | 0.150 | 0.157 |
| L | 0.400 | 1.270 | 0.016 | 0.050 |
| θ | 0° | 8° | 0° | 8° |




Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.